

November 2013

# FJN3302R NPN Epitaxial Silicon Transistor with Bias Resistor

## **Features**

- 100 mA Output Current Capability
- Built-in Bias Resistor ( $R_1 = 10 \text{ k}\Omega$ ,  $R_2 = 10 \text{ k}\Omega$ )

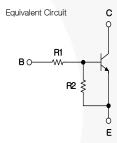
## **Applications**

- Switching, Interface, and Driver Circuits
- Inverters
- · Digital Applications in Industrial Segments



## Description

Transistors with built-in resistors can be excellent space- and cost-saving solutions by reducing component count and simplifying circuit design.



## **Ordering Information**

ſ	Part Number	Top Mark	Package	Packing Method
	FJN3302RTA	R3302	TO-92 3L	Ammo

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^{\circ}\text{C}$  unless otherwise noted.

Symbol	Parameter	Value	Unit
V <sub>CBO</sub>	Collector-Base Voltage	50	V
V <sub>CEO</sub>	Collector-Emitter Voltage	50	V
V <sub>EBO</sub>	Emitter-Base Voltage	10	V
I <sub>C</sub>	Collector Current	100	mA
T <sub>J</sub>	Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature	-55 to 150	°C

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## Thermal Characteristics(1)

Values are at  $T_A = 25^{\circ}C$  unless otherwise noted.

Symbol	Parameter	Value	Unit
В	Power Dissipation	300	mW
P <sub>D</sub>	Derate Above T <sub>A</sub> = 25°C	2.4	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	416	°C/W

### Note:

## **Electrical Characteristics**

Values are at  $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 10 \mu A, I_E = 0$	50			V
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage	$I_C = 100 \mu\text{A},  I_B = 0$	50			V
I <sub>CBO</sub>	Collector Cut-Off Current	$V_{CB} = 40 \text{ V}, I_{E} = 0$			0.1	μΑ
h <sub>FE</sub>	DC Current Gain	$V_{CE} = 5 \text{ V}, I_{C} = 5 \text{ mA}$	30			
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	$I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$			0.3	V
$f_T$	Current Gain Bandwidth Product	$V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$		250		MHz
C <sub>ob</sub>	Output Capacitance	$V_{CB} = 10 \text{ V}, I_{E} = 0,$ f = 1.0 MHz		3.7		pF
V <sub>I</sub> (off)	Input-Off Voltage	$V_{CE} = 5 \text{ V}, I_{C} = 100 \mu\text{A}$			0.5	V
V <sub>I</sub> (on)	Input-On Voltage	$V_{CE} = 0.3 \text{ V}, I_{C} = 10 \text{ mA}$	3			V
R <sub>1</sub>	Input Resistor		7	10	13	kΩ
R <sub>1</sub> /R <sub>2</sub>	Resistor Ratio		0.9	1.0	1.1	

<sup>1.</sup> PCB size: FR-4 76 x 114 x 0.6T mm<sup>3</sup> (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.

## **Typical Performance Characteristics**

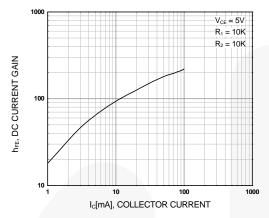


Figure 1. DS Current Gain

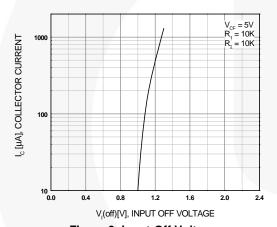


Figure 3. Input-Off Voltage

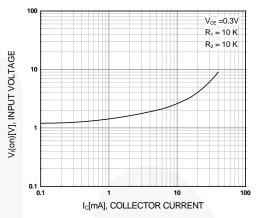


Figure 2. Input-On Voltage

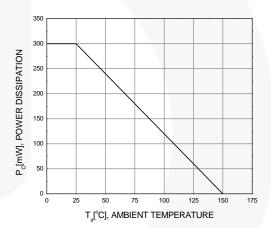


Figure 4. Power Derating

## **Physical Dimension**

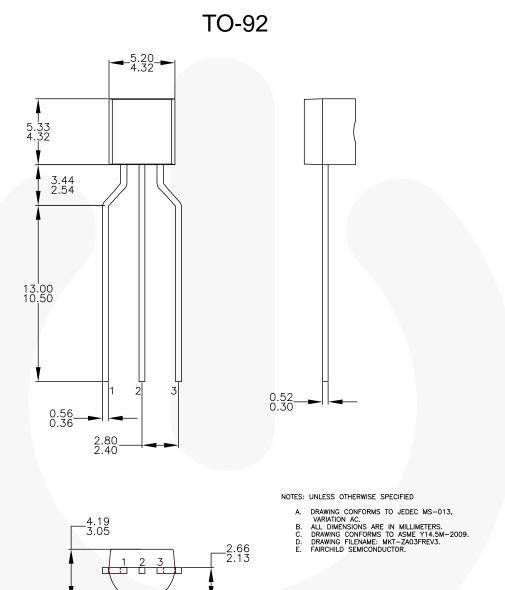


Figure 5. 3-LEAD, TO-92, MOLDED 0.200 IN-LINE SPACING LD FORM (J61Z OPTION) (ACTIVE)

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Definition of Terms		
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